REMARKS

Claim 1 has been amended in order to more particularly point out, and distinctly claim the subject matter to which the applicant regards as his invention. The applicant respectfully submits that no new matter has been added. It is believed that this Amendment is fully responsive to the Office Action dated May 19, 2005.

Claim 2 has been canceled without prejudice or disclaimer. Claims 3 - 10 were canceled, similarly without prejudice or disclaimer, during the filing of this Divisional application. Independent claim 1 is currently pending in this patent application.

In the outstanding Action, the Examiner maintains his reliance on Hiraoka (U.S. Patent No. 6,465,742) in rejecting claims 1 and 2 under 35 USC §102(e) as being anticipated by Hiraoka. The applicant respectfully requests reconsideration of this rejection.

The applicant has incorporated the subject matter of claim 2 into independent claim 1, and submits that amended claim 1 should now be allowable for the reasons discussed below.

The applicant's claimed multilayer circuit board has a conductive part including the electric conductive sections, which will be formed into cable patterns, and the post vias.

In each cable layer, tops of the electric conductive sections and a top of the first insulating layer are in the same plane (i.e., the height of the electric conductive sections are equal to that of the first insulating layer enclosing those electric conductive sections); and tops of the post vias and a top of the second insulating layer are in the same plane (i.e., the height of the post vias are equal to that of the second insulating layer). The claimed multilayer circuit board is constituted by the above described cable layers.

The electric conductive sections are abraded until their thicknesses are made equal to that of the first insulating layer. The post vias are abraded until their thicknesses are made equal to that of the second insulating layer. The electric conductive sections are formed by being filled in the first insulating layer with prescribed patterns. The post vias are formed by being filled in the second insulating layer.

The applicant further submits that in his claimed invention, the surfaces of the first insulating layer, which includes the electric conductive sections, and the second insulating layer, which includes the post vias, are made perfectly flat. By making the surfaces of the insulating layers flat without undulations, the cable patterns are not blurred in the exposing process so that fine cable

patterns can be formed with high accuracy.

On the other hand, in Hiraoka, cable patterns and post vias are formed in the same insulating layer. However, the applicant's novel and non-obvious claimed structural arrangement in their claimed invention (i.e., the cable patterns or the electric conductive sections and the post vias being formed in different insulating layers) is not disclosed and suggested in the cited reference.

In view of the above, since not all of the claimed elements, as now set forth in independent claim 1 (as amended), are found in exactly the same situation and united in the same way to perform the identical function in Hiraoka's apparatus, there can be no anticipation under 35 USC §102(e) of the applicant's claimed multilayer circuit board based on the Hiraoka reference.

Accordingly, the withdrawal of the outstanding anticipation rejection under 35 USC §102(e) based on Hiraoka (U.S. Patent No. 6,465,742) is in order, and is therefore respectfully solicited.

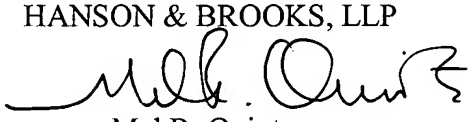
In view of the aforementioned amendments and accompanying remarks, claims, as amended, are in condition for allowance, which action, at an early date, is requested.

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact the applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, the applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper to Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, KRATZ, QUINTOS,
HANSON & BROOKS, LLP



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